



IoT SIM

Global and Europe IoT Connectivity: Unleash the power of your applications with our advanced M2M SIM card or embedded SIM (eSIM)

Our advanced IoT connectivity package offers seamless coverage both globally and in Europe.









- For **global coverage**, connect in **150** countries and over **600** network operators
- For **European coverage**, connect in **39** countries across Europe

Benefit from Remote SIM Provisioning (RSP) technology, compliant with GSMA SGP.02 standards. Choose between standard SIM cards or SMD modules (MFF2/QFN8) for added flexibility. Rely on SmartCard-based technology for high security. Easily manage from individual devices to entire fleets via our connectivity management platform, AirOn360® IoT Suite. Ensure adherence to industry standards and data protection laws. Additionally, send unlimited SMS from AirOn360® IoT Suite to your device, with an optional SMS top-up available for MO SMS after acquiring your IoT SIM.



Product Specifications

SIM Features

-  Remote Provisioning
-  End-to-end Security
-  Reduced Logistics
-  Scalability
-  Flexibility
-  Wide Coverage
-  Standard Compliance
-  Regulatory Compliance



Robust Hardware



Powerful Platform



Premium Support

Technical Details

Technical specifications	Triple cut	MFF2
Coverage type (LTE/3G/LTE-M etc.)	LTE/3G/LTE-M	LTE/3G/LTE-M
Data retention	10 years at 25 °C	17 years at 25 °C
Operating temperature range	-25 to 85 °C / -13 to 185 °F	-40 to 105 °C / -40 to 221 °F
Grade (Consumer, Industrial etc.)	Consumer	Industrial
Compliance (GSMA)	SGP.01, SGP.02 V4.2	SGP.01, SGP.02 V4.2
Operating Voltage	3,3V, 1,8V +-10%	5,0V, 3,3V, 1,8V +-10%
Memory (NVM)	2.0MB Flash	1.2 MB Flash
Memory (SRAM)	50kB	30 kB RAM
Write Endurance	Min. 100.000 erase/write cycles for page at 25 °C	Min. 500.000 erase/write cycles for page at 25 °C
Software features	Java Card 3.0.5 GlobalPlatform v2.3 GlobalPlatform Amd. A, B, D, E, F	Java Card 3.0.5 GlobalPlatform v2.3 GlobalPlatform Amd. A, B, D, E, F
Interface	ISO/IEC 7816- 3	ISO/IEC 7816- 3
ETSI 102 671 Specification	TS-RA-UA	TB-MA-HA-CA-VA-SA-RC-UB
Housing / Form Factor	Triple cut SIM (2FF/2FF/4FF) - ABS material	MFF2 (ETSI 102 671 definition)

Effortlessly manage your IoT deployments

Gain full **access** to our cutting-edge AirOn360® IoT Suite upon acquiring any of our SIMs.

With its intuitive interface and extensive range of features, IoT Suite **removes the obstacles typically involved with monitoring numerous devices and managing global connectivity services from various network operators.**



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